

**Amendments to the Claims**

Claims 1-50 (Cancelled).

51. (Currently amended) A method of forming a plurality of microelectronic lids, comprising:

forming a lid stock material into a shape of a bar having a length, having a first side, having a groove extending along the first side, and having a second side opposing the first side, the first and second sides having substantially equivalent widths, with the second side being substantially planar across the width; ~~and having a groove extending along the first side;~~

after forming the lid stock material into the shape, cutting the bar along the length to form a plurality of separated microelectronic lids; and

wherein the lid stock material comprises aluminum or copper, and further comprising electroplating the separated microelectronic lids with nickel.

52. (Previously presented) The method of claim 51 wherein the forming the lid stock material into the shape comprises extruding the lid stock material into the shape.

53. (Previously presented) The method of claim 51 wherein the forming the lid stock material into the shape comprises:

providing a bar of the lid stock material that lacks the groove in the side; and  
machining the groove into the side of the bar.

54. (Previously presented) The method of claim 51 wherein the lid stock material comprises aluminum.

55. (Previously presented) The method of claim 51 wherein the lid stock material comprises copper.

56. (Previously presented) The method of claim 51 further comprising incorporating at least one of the microelectronic lids into a microelectronic package, the incorporating comprising:

providing a chip supported by a base; and

adhering the microelectronic lid to the base and over the chip; the chip accordingly being packaged between the microelectronic lid and the base.